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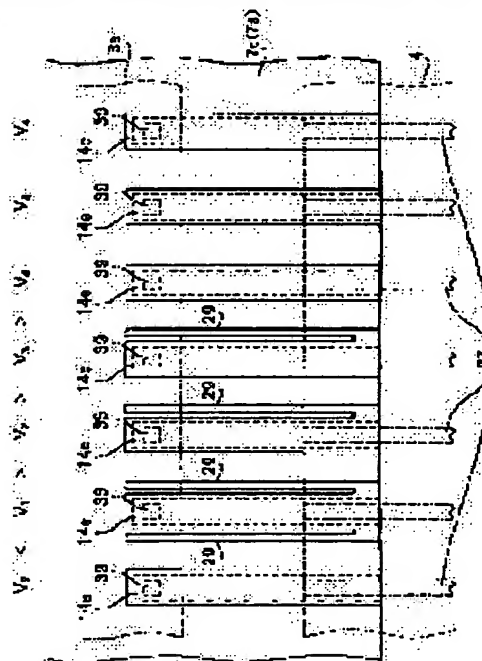
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## (54) WIRING BOARD, DISPLAY, SEMICONDUCTOR CHIP AND ELECTRONIC APPARATUS

(57)Abstract:

PROBLEM TO BE SOLVED: To prevent the corrosion of metal wirings of a wiring pattern made of a metal material having a low electric resistance.

SOLUTION: The wiring board has a plurality of metal wirings 14e on a board 7c. A guard wiring 29 made of a conductive oxide such as ITO, etc., is formed between at least a pair of adjacent metal wirings among the wirings 14e. When voltages V1-V4 ( $V1 > V2 > V3 > V4$ ) are applied to the wirings 14e, inserting the guard wiring 29 between the metal wirings 14e at the anode side and the metal wiring 14e at the cathode side prevents the wiring 14e at the anode side from corroding.



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